



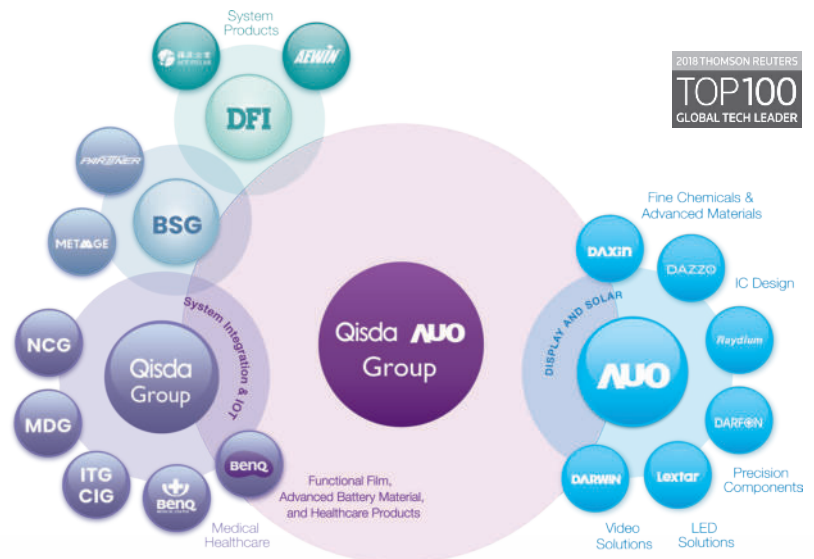
Fueling the Future of the Smart Energy Sector

DFI's Rugged and Flexible Edge AI Computing Lineup
Drives Innovation for the Energy of Tomorrow

Plan the Energy Production with DFI Edge AIoT Innovation

About DFI

DFI, a subsidiary of QISDA Group (ranked among the 2018 Top 100 Global Technology Leaders), was established in 1981 and has since become a global leader in high-performance computing products for a wide range of embedded industries. In addition to offering Commercial off-the-shelf (COTS) products, DFI also specializes in ODM/OEM design services, creating customized services to meet the unique needs of each customer. These tailored capabilities are reflected in DFI's industrial-grade AIoT offerings, which combine innovation and quality to enhance energy infrastructure reliability, extend lifecycles, and ensure 24/7 performance.



Comprehensive One-Stop Service

01

DFM Alignment

DFI experts leverage DFM principles and work closely with customers to refine designs, specifications, and BOMs, while extending product lifespans to ensure every delivery meets rigorous standards.

02

Tailored Customization & Rigorous Validation

Delivering not only commercial off-the-shelf products but also tailored offerings—including custom x86/ARM-based platforms, prototyping, rigorous power and signal validation, performance optimization, and certification to meet industry standards—we are committed to building the most resilient, quality-driven products.

03

Value-Added Technology

Offering value-added technologies such as software integration (Windows, RTOS, Ubuntu, Android), BIOS/firmware optimization (Slim Bootloader, fast resume, 1W low-power standby), AI acceleration, and Out-of-Band modules to meet the diverse needs of smart energy applications.

04

100% In-house Production

All in-house production, from PCB assembly to final testing, with key components sourced outside of China, ensures supply chain stability, risk reduction, and consistent product quality for smart energy applications.

05

After Service

Comprehensive post-production support with long-term availability, including repairs, upgrades, re-order fulfillment, and BOM management, ensuring continuous lifecycle support for diverse energy applications.

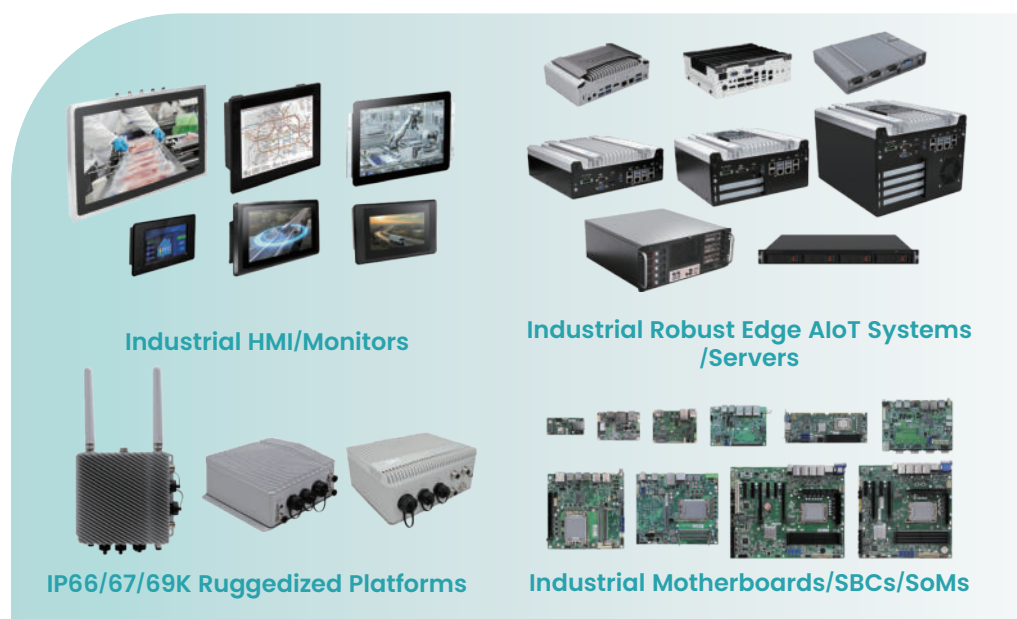
DFI Delivers Premium Edge AI Platforms for the Global Energy Market

Tailored for a Variety of IoT Energy Applications

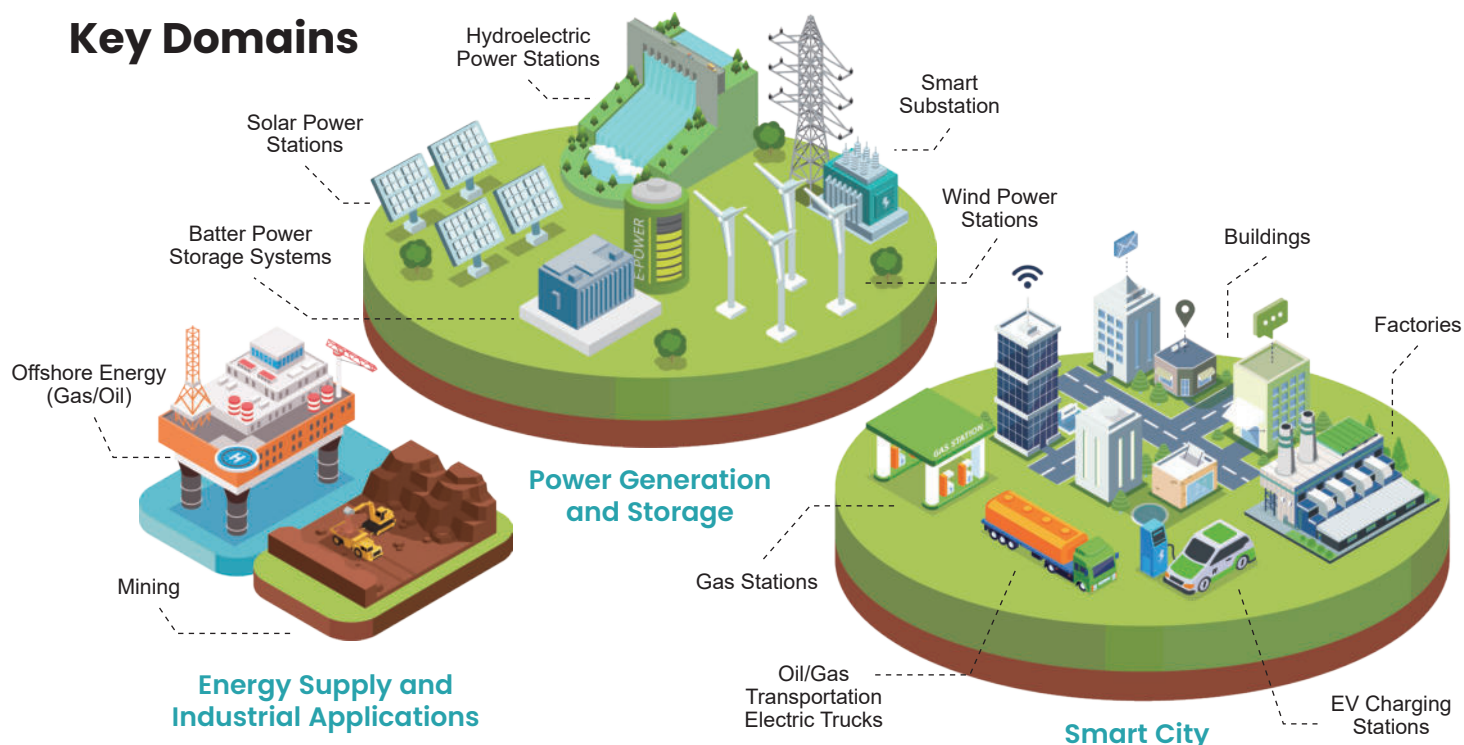
With the rapid growth of IoT, the energy industry has become a key focus. DFI's Industrial Edge AI platforms seamlessly integrate sensing, real-time control, monitoring, and remote communication, meeting the stringent demands of energy applications worldwide.

We offer durable, reliable, and flexible embedded AIoT platforms in various sizes and configurations to support the needs of energy automation.

DFI Edge AIoT Products



Key Domains

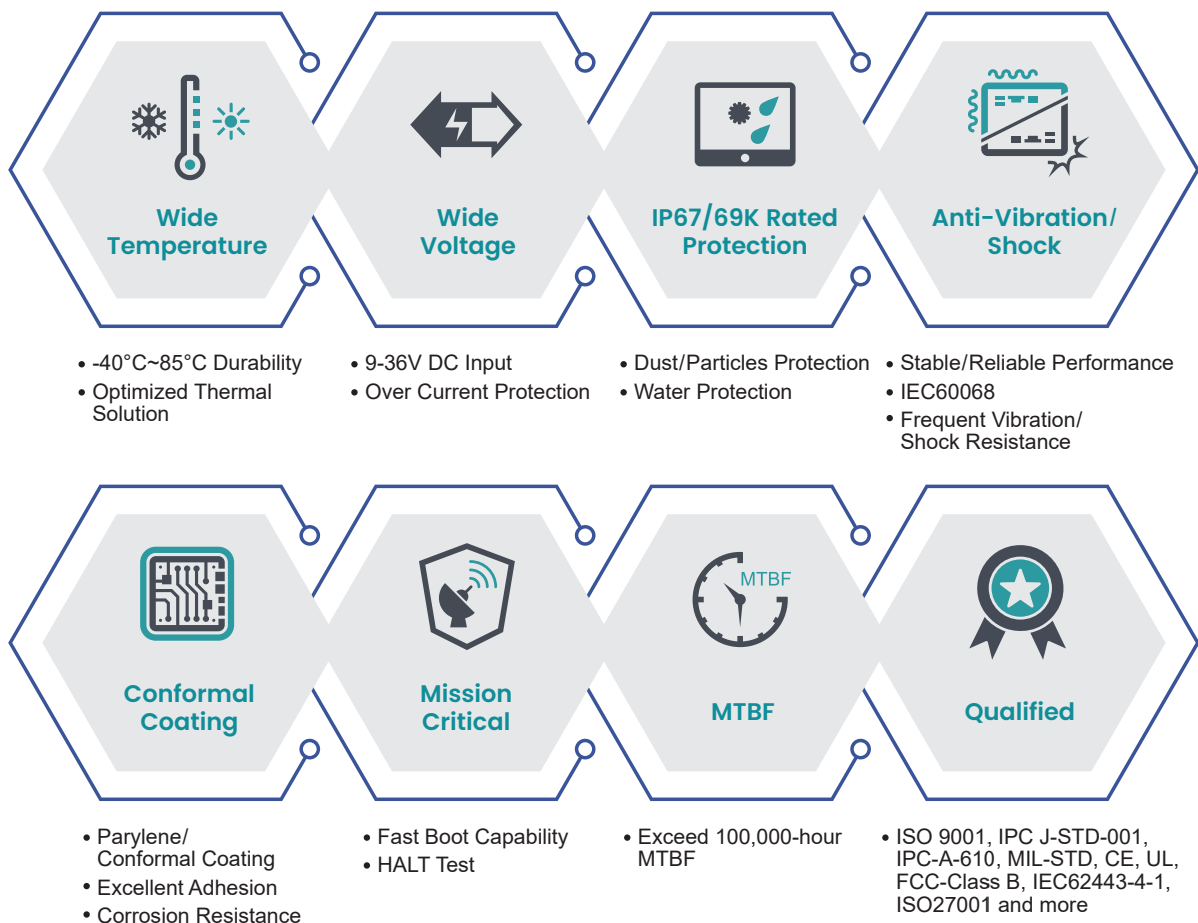


Flexibility, Ruggedized & Custom Design for Extreme Applications

Powered by Flexibility, Agility, and Reliability

DFI offers flexible embedded computing platforms for energy applications that require strict design and performance standards, especially for reliable operation in extreme environments. Widely adopted across energy management, smart grids, renewable energy, and oil and gas sectors, our AIoT platforms with ruggedized design optimize operational efficiency, extend equipment lifespan, and provide ongoing support to ensure the stability and security of energy systems.

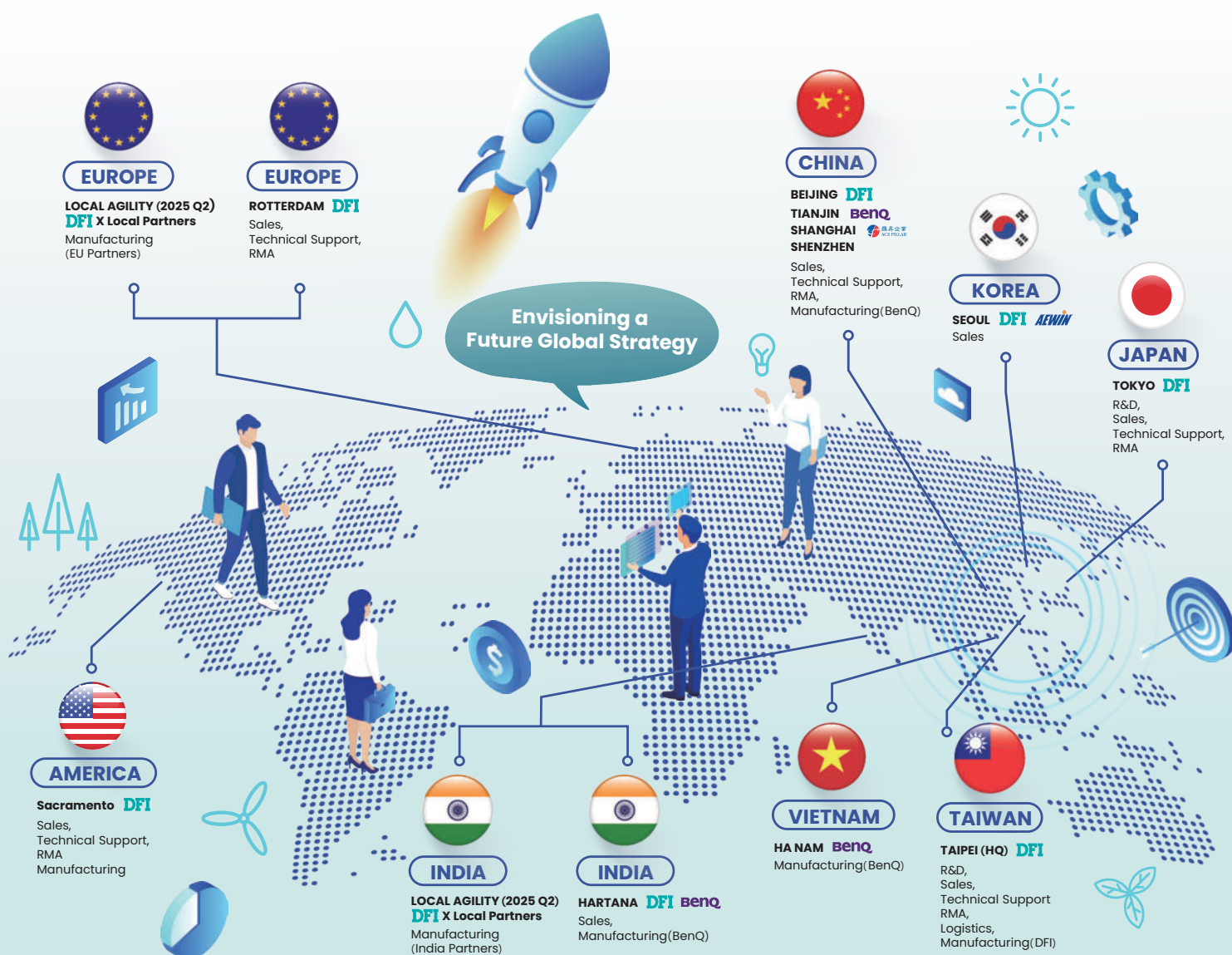
DFI's Edge AIoT Platforms Feature a Broad Range of Ruggedized Designs



Global Reach, Driven by DFI's Unmatched Design, Manufacturing, and Service Excellence



DFI deepens its 'Global Reach, Local Agility' strategy by integrating Qisda Group resources to strengthen supply chain flexibility and local production service capabilities. Additionally, we assess the potential impact of geopolitical and tariff changes on operations, optimizing manufacturing and logistics layouts to reduce overall operational risks. At the same time, we actively strengthen collaboration with local supply chain partners and customers, providing more efficient and integrated technical support and services, accelerating the implementation of AI applications, and solidifying market competitiveness.



High-Demands Models

EC900-8MM | Ultra Compact Fanless System



Compact IoT gateway with NXP i.MX8M Mini, built for ultra-low power edge use with flexible I/O and dual M.2 slots

- Ultra low power NXP i.MX8M Mini IoT Gateway (max. 6.4W)
- LPDDR4 3200MHz memory down, up to 8GB
- Yocto 3.3 supported
- 2 GbE LAN, 2 USB, 4bit DIO, RS422, RS485, 2x M.2 slots
- 9~36VDC in

EC700-ASL | Ultra Compact Fanless System



Ultra slim fanless system with Intel® Atom x7000, LPDDR5, TSN-ready 2.5GbE, and wide-temp support for edge use

- Ultra slim Intel® Atom x7000 fanless embedded system
- 8GB/16GB LPDDR5 4800 Memory down
- 2 2.5GbE ports with TSN support
- 1 VGA, 1 HDMI, 1 USB type C, 4 COM, DIO, 3 USB 3.2, Audio
- -40°C~60°C operating temperature

ECX700-ADP | Ruggedized System



IP67/69K fanless system with 12th Gen Intel® Core™ i7, -20°C~70°C, M12 I/O, SIM slot, 9~36V DC input for extreme edge applications

- IP67/69K Extreme Rugged System with 12th gen. Intel® Core i7 processor
- Fanless at -20 ~ 70°C operating temperature
- HDMI, 2 GbE, 2 USB 3.2, 2 CAN bus/ 2 COM at M12 D-coded connectors
- External accessible SIM slot
- DC in 9~36V

ECX700-AL | Ruggedized System



IP67/69K fanless system with Intel® Atom® E3900, -40°C~70°C operating range, M12 I/O, LTE/Wi-Fi support, and 9~36V DC input

- IP67/69K Extreme Rugged System with Intel® Atom® E3900 Processor
- Fanless at -40°C~70°C operating temperature
- HDMI, 2 GbE, 2 USB 3.0, 2 CAN bus/ 2 COM at M12 D-coded connectors
- Optional LTE and Wifi integrated with external accessible SIM slot
- DC in 9~36V

X6-ORN | AI Inference System



Compact AI system with Jetson Orin Nano™/NX, 4 GbE (2x PoE optional), rich I/O, triple M.2, and 9~36V DC for edge AI computing

- Compact NVIDIA® Jetson Orin Nano™ / NX embedded system
- Four RJ45 GbE ports and optional 2x PoE
- Multiple Expansions: 1 M.2 2230 E-Key, 1 M.2 2280 M-Key, 1 M.2 3042/3052 B-Key
- Rich I/O: Audio, RS232/485, CAN bus, 2 USB 3.2, DIO, HDMI
- DC in 9~36V

EC600-RPS | Embedded Fanless System



High-performance fanless system with Intel® Core™, DDR5 memory, extensive I/O, and 5x M.2 expansion for industrial edge applications

- Expandable embedded system with 14th Gen Intel® Core™ processor, up to 65W TDP
- Supports DDR5 SODIMM-4800 up to 64GB
- 2 2.5GbE, 4 GbE(or 2GbE, 2 PoE), 10 COM, 5 USB 3.2(Gen2x1), 1 USB Type-C
- Multiple Expansion: 5 M.2 slots, 1 mini-PCIe slot (full size)
- Up to -20°C~70°C operating temperature and DC in 9~36V

EC633-RPS | Embedded Fanless System



Expandable fanless system with Intel® Core™, and rich I/O for high-performance industrial edge computing

- Expandable embedded system with 14th Gen Intel® Core™ processor, up to 65W TDP
- Supports DDR5-4800 SODIMM up to 64GB
- 2 2.5GbE, 4 GbE(or 2 GbE, 2 PoE), 10 COM, 5 USB 3.2(Gen2x1), 1 USB Type-C
- Multiple Expansion: 5 M.2 slots, 1 mini-PCIe slot (full size)
- Supports 2 PCIe x8 and 1 PCIe x4, up to 300W PEG card

EC70A-MTH | Ultra Compact Fanless System



Ultra compact fanless system with Intel® Core™ Ultra processor, up to 64GB LPDDR5/x, triple LAN, rich I/O, wide-temp support, and versatile M.2 expansions

- Compact fanless system with Intel® Core™ Ultra processor
- Dual Channel LPDDR5/x 6400MHz memory down up to 64GB
- 2 2.5GbE, 1 GbE, 5 USB 3.2, 1 USB-C, 4 COM, HDMI
- -20°C~70°C fanless operating temperature
- 1 M.2 M Key, 1 M.2 B Key, 1 M.2 E Key multiple expansions

RM646-ERX810 | Edge AI Server



4U Edge AI server with dual Xeon® CPUs, 1024GB ECC RAM, triple GPU, Gen 5 PCIe, and rich I/O for high-performance edge workload

- 4U Rackmount Edge-Server with dual 5th/4th Gen Intel® Xeon® Scalable processors
- 16 ECC-RDIMM up to 1024GB
- Supports up to 3 dual width, full length, full height GPU cards
- Multiple Expansion Options: 4 PCIe x16 (Gen 5), 2 PCIe x8 (Gen5), 1 M.2 M key 2280
- Diverse I/O Options: 4 GbE, 1 dedicated IPMI LAN, 4 USB 3.2, 1 DP

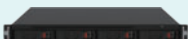
ED700-EHL | Ultra Compact Fanless System



DIN rail ultra compact fanless system with Intel® Atom x6000, up to 32GB DDR4, isolated COM & DI/DO, -40°C~60°C wide-temp, and 5G support with dual SIM

- DIN Rail compact system with Intel® Atom x6000 processor
- Dual channel DDR4-3200 memory by soldered onboard and one SODIMM, up to 32GB
- Dual 2KV isolated COM ports and 12bit DI/DO
- Supports up to -40°C~60°C operating temperature (Intel® Embedded Series)
- Supports 5G module with dual SIM

RM810-ERX810 | Edge AI Server



1U Edge AI server with dual Intel® Xeon® CPUs, up to 1024GB RDIMM, PCIe Gen 5, rich I/O, IPMI remote management, and 4 hot-swappable 3.5" drive bays

- Slim 1U Rackmount – Space-saving design with dual 5th/4th Gen Intel® Xeon® Scalable CPU support
- High-Capacity Memory – Up to 1024GB RDIMM across 16 slots for data-intensive workloads
- Flexible Expansion & I/O – 1 PCIe x16, 4 GbE, 1 IPMI LAN, 4 USB 3.2, 1 DP, 1 M.2 (2280 M-Key), 2 MCIO
- IPMI-based out-of-band management for remote system monitoring and control
- 4 hot-swappable 3.5" drive bays ensure high-availability and serviceability

KS Series | Panel PC



KS Series fanless touch panel PCs feature versatile sizes (5.7"~21.5"), powered by x86 and ARM platforms with Linux/Android support, open-frame design, and 9~36V DC input

- Versatile size All in One PCs at 5.7", 7", 10", 10.1", 15", 15.6", 17", 21.5" Industrial Touch Panel
- From entry to performance Intel® platforms: Atom®, Core™, and Celeron®
- Offer low power ARM NXP i.MX8M, NXP i.MX6, TI® AM3517 platforms with Linux/Android OS support
- Provides open frame options with flexibility on housing design
- Fanless and DC 9~36V input

KSX215P-EHL | Panel PC



21.5" IP69K stainless touch panel PC with Intel® Atom x6000, M12 I/O, 9~36V input, and M.2/SIM expansion for rugged, hygienic environments

- IP69K 21.5" Touch Panel PC with Intel® Atom X6000 processor
- Construction 304 Stainless steel chassis
- Multiple Expansions 1 x M.2 2242/2280/3052 B Key, 1 x M.2 2230 E Key, 1 x Nano SIM
- 1 RS232, 2 USB 2.0, 1 GbE @ M12 waterproof connectors
- Wide Voltage Support 9-36V @ M12 connector

JUR101-TGU | Rugged Tablet



10.1" rugged tablet with 11th Gen Intel® Core™, sunlight-readable display, hot-swappable dual batteries, Dragontrail™ glass, and programmable function keys

- Rugged High Brightness Sunlight-Readable 10.1" Tablet with 11th Gen Intel® Core™ Processors
- ALL-DAY usability with hot swap capability (2 removable Li-Ion battery)
- Optical bonding enhances both visibility and strength
- Chemically-strengthened Dragontrail™ High Ion-Exchange (HIE™) cover glass for excellent impact and scratch resistance
- Adjustable LED backlit keys and 8x programmable function keys



ARH171/173 | Mini-ITX Motherboard



Intel® Arrow/Meteor Lake H/U-based Mini-ITX with quad displays and rich expansion

- Arrow Lake H Intel® Arrow Lake H/U, Meteor Lake H/U Processors
- 2 DDR5 SODIMM up to 64GB
- Quad Displays: 2 DP/HDMI + 1 USB Type C + 1 M2A Display (eDP/LVDS/VGA/HDMI/DP)
- Multiple Expansion: 1 PCIe x4, 1 M.2 M key, 1 M.2 B key, 1 M.2 E Key, 1 M.2 A Key
- Rich I/O: Up to 3 Intel® 2.5GbE, 4 USB 3.2 Gen2, 1 USB Type C and 4 USB 2.0 headers

HPT171 | Mini-ITX Motherboard



An AMD® Ryzen™ Embedded 8000 Series Mini-ITX Motherboard featuring extensive I/O options and multiple expansion capabilities

- AMD® Ryzen™ Embedded 8000 Series Processors
- 2 DDR5 5600MHz SODIMM up to 64GB
- Quad display: 4 DP++ or 3 DP++ + 1 M.2 A display
- Multiple expansion: 1 PCIe Gen4 x16 Slot (x8 Signal), 1 M.2 M key, 1 M.2 A key (LVDS/eDP/HDMI/DP/VGA) and M21(PCIE/-SIM/USB3/USB2) module support, 1 DFI eMMC modular port
- Rich I/O : 2 2.5GbE RJ45, 2 USB 3 Type-A, 2 USB2.0 Type A, 2 COM D-Sub, 1 Audio Jack Line-IN/Line-OUT/Mic-IN, 4 RS232(ccTalk/TTL), 4 USB2.0 headers, Gaming I/O(PCIE,UART/USB2.0,Audio)

ASL171/173 | Mini-ITX Motherboard



Optimized for industrial applications with Intel® Atom® Amston Lake processors and dual 2.5GbE LAN for reliable, high-speed connectivity

- Arrow Lake H Intel® Arrow Lake H/U, Meteor Lake H/U Processors
- 2 DDR5 SODIMM up to 64GB
- Quad Displays: 2 DP/HDMI + 1 USB Type C + 1 M2A Display (eDP/LVDS/VGA/HDMI/DP)
- Multiple Expansion: 1 PCIe x4, 1 M.2 M key, 1 M.2 B key, 1 M.2 E Key, 1 M.2 A Key
- Rich I/O: Up to 3 Intel® 2.5GbE, 4 USB 3.2 Gen2, 1 USB Type C and 4 USB 2.0 headers

ARS630 | ATX Motherboard



ATX motherboard with Intel® Arrow Lake-S, up to 192GB DDR5, quad display support, rich I/O, and multiple expansion options

- Intel® Core™ Ultra Arrow Lake-S Processors, W880/Q870
- 4 DDR5-5600 ECC/NON-ECC UDIMM up to 192GB
- Quad Displays: 1 VGA, 2 DP++, 1 HDMI
- Multiple Expansion: 2 PCIe x16 (Gen5, x16 or x8+x8), 4 PCIe x4 (1 Gen5; 3 Gen4), 1 PCI, 2 M.2 M key (1 Gen5; 1 Gen4), 1 M.2 E key, 1 M.2 A Key (for OOB)
- Rich I/O: Up to 4 Intel® 2.5GbE, 4 USB 3.2 Gen2, 6 USB 3.2 Gen1 and 3 USB 2.0, 6 COM, 4 SATA

RAP310 | microATX Motherboard



Powered by AMD® Ryzen™ 7000 Series, delivers triple display support, flexible expansion, and rich I/O connectivity

- AMD® Ryzen™ 7000 Series with AMD B650 chipset
- Triple displays: 1 VGA, 1 DP++, 1 HDMI
- Multiple expansion: 2 PCIe x16, 2 PCIe x4, 1 M.2 E key, 1 M.2 M key, 4 SATA 3.0
- 4 DDR5 UDIMM up to 128GB
- Rich I/O: 2 Intel® 2.5GbE, 4 COM, 6 USB 3.2 Gen2, 2 USB 3.2 Gen1, 6 USB 2.0

ERX810 | EATX Motherboard



High-performance EATX motherboard powered by Intel® Xeon® Scalable processors, supporting up to 1024GB DDR5 ECC memory and advanced remote management

- 5th/4th Gen Intel® Xeon® Scalable Family
- 16 DDR5 ECC-RDIMM up to 1024GB
- IPMI OOB Remote Management
- Multiple Expansion: 4 PCIe x16 (Gen 5), 2 PCIe x8 (Gen5), 1 M.2 M key 2280
- Rich I/O: 4 Intel® GbE, 1 Dedicated IPMI LAN, 2 COM, 4 SATA 3.0, 6 USB 3.2 Gen1, 3 USB 2.0

MTU9A2 | COMe Mini



MTU9A2 with Intel® Core™ Ultra U-Series, up to 16GB LPDDR5, dual displays, PCIe expansion, and rich I/O in a compact COMe Type 10 Mini form factor

- Intel® Core™ Ultra Processor (Series 1), U-series only
- Single Channel LPDDR5 7467MHz up to 16GB
- Dual Displays: 1 DDI + 1 LVDS/eDP
- Multiple Expansion: 4 PCIe x1, 1 I2C, 1 SMBus, 1 x LPC/eSPI, 2 x UART
- Rich I/O: 1 Intel 2.5GbE, 2 USB 3.2, 8 USB 2.0, 2 SATA 3.0

ASL9A2 | COMe Mini



ASL9A2 combines Intel® Atom® performance with dual display, high-speed memory, and scalable expansion in a compact form

- Intel® Atom® Processor Amston Lake Series
- Dual Channel LPDDR5 4800MHz up to 16GB
- 1 LVDS/eDP, 1 DDI (HDMI/DP++) : Supports dual displays: DDI + LVDS/eDP
- Multiple expansions: 4 PCIe x1, 1 SMBus, 1 I2C, 1 eMMC
- Rich I/O: 1 Intel® 2.5GbE, 2 SATA 3.0, 2 USB 3.1, 8 USB 2.0

MTH966 | COMe Compact



COMe Type 6 module with Intel® Core™ Ultra, up to 64GB LPDDR5, multi-display support, extensive PCIe expansion, and rich I/O for embedded solutions

- Intel® Core™ Ultra Processor (Series 1/2)
- Dual Channel LPDDR5 7467MHz memory down up to 64GB
- Multiple Displays: 1 VGA + 1 LVDS/eDP + 3 DDI
- Multiple Expansion: 8 PCIe x1, 2 PCIe x4, 1 PCIe x8, 1 I2C, 1 SMBus, 1 LPC/eSPI, 2 UART
- Rich I/O: 1 Intel® 2.5GbE, 2 USB 4.0, 3 USB 3.2, 8 USB 2.0, 2 SATA 3.0

ASL600 | SMARC



SMARC 2.2 module with Intel® Atom x7000RE, up to 16GB LPDDR5, triple display, rich I/O, and PCIe Gen3 expansion for low-power edge applications

- Intel® Atom x7000RE series processors (Code Name: Amston Lake/Twin Lake)
- Onboard LPDDR5 4800MHz up to 16GB
- Triple Displays: 1 LVDS/eDP, 1 HDMI, 1 DDI
- Multiple Expansion: Up to 4 PCIe x1 (Gen3)
- Rich I/O: 2 2.5GbE, 2 USB 3.2, 4 USB 2.0, 1 SATA 3.0

QCS051 | 2.5" SBC



Combines thin-client efficiency and rugged design, built on the Qualcomm® QCS6490 platform

- Qualcomm QCS6490 high-level platform
- Target on AMR, box PC application
- Thin client concept and ruggedize
- 2 M.2 Expansions: 1 M.2 E key 2230, 1 M.2 B key 3052
- Supports CPU Life Cycle Until 2036

ASL051 | 2.5" SBC



Featuring Intel® Atom x7000RE series (Amston Lake/Twin Lake), ASL051 delivers efficient computing for space-constrained and I/O-rich environments

- Intel® Atom x7000RE series processors (Code Name : Amston Lake/Twin Lake)
- 1 DDR5 4800MHz SODIMM
- Dual Displays: HDMI + LVDS/eDP (Opt.)
- Multiple Expansion: 1 M.2 E Key, 2 M.2 B Key
- Rich I/O: 2 Intel® 2.5GbE, 2 COM, 2 USB 3.2, 2 USB 2.0

IRN556 | 3.5" SBC



Designed for Edge IoT applications, featuring Intel® Atom x7000RE for low-power, high-efficiency edge computing

- Intel® Atom x7000RE series processors (Code Name : Amston Lake/Twin Lake)
- 1 DDR5 4800MHz SODIMM
- Dual Displays: HDMI + LVDS
- Multiple Expansion: 1 M.2 E Key, 1 M.2 B Key, 1 M.2 M Key
- Rich I/O: 2 Intel® GbE, 4 COM, 4 USB 3.2, 2 USB 2.0

MTH556 | 3.5" SBC



Designed for Edge AI inference, MTH556 combines Intel® Core™ Ultra, triple display, and flexible expansion

- Intel® Core™ Ultra Processor Series 1/2
- 2 DDR5-5600 SODIMM up to 96GB
- Triple Independent Displays: 1 HDMI, 1 LVDS, 1 USB-C DP Alt. mode
- Multiple Expansion: 1 M.2 M Key, 1 M.2 B Key, 1 M.2 E Key
- Rich I/O: 2 2.5GbE, 4 COM, 3 USB 3.2, 1 USB-C